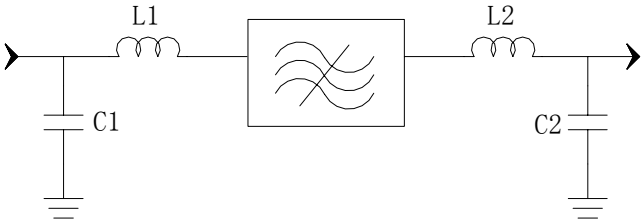
Specifications

Parameter	Unit	Minimum	Typical	Maximum
Center Frequency	MHz	132.4	132.5	132.6
Insertion Loss	dB	-	24.6	25
1 dB Bandwidth	MHz	4.6	4.7	-
3 dB Bandwidth	MHz	5	5.2	-
40 dB Bandwidth	MHz	-	6.83	7
Passband Variation	dB	-	0.6	1
Absolute Delay	usec	-	1.856	3.5
Ultimate Rejection	dB	45	49	-
Material Temperature coefficient	KHz/°C	25		
Ambient Temperature	°C	0.1325		
Package Size	DIP2212 (22.2x12.8x4.7mm3)			

Notes:

1. All specifications are based on the test circuit shown
2. In production, devices will be tested at room temperature to a guardbanded specification to ensure electrical compliance over temperature
3. Electrical margin has been built into the design to account for the variations due to temperature drift and manufacturing tolerances
4. This is the optimum impedance in order to achieve the performance show

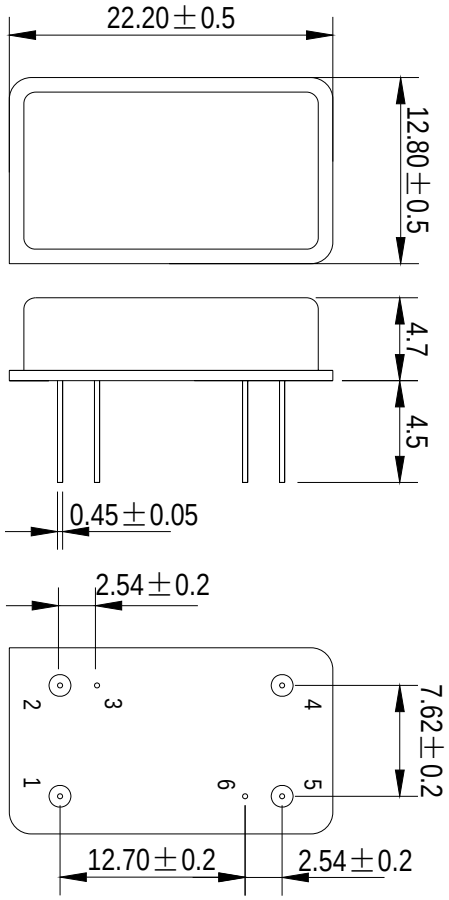
Matching Configuration



L1=150nH L2=120nH
C1=36pF C2=39pF
Source/Load Impedance=50 ohm

Notes - Component values may change depending n board layout.

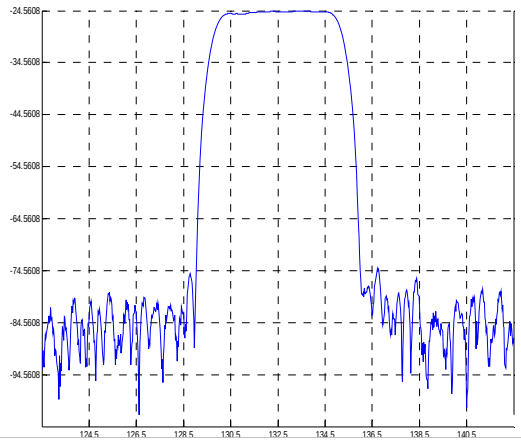
Package Dimension



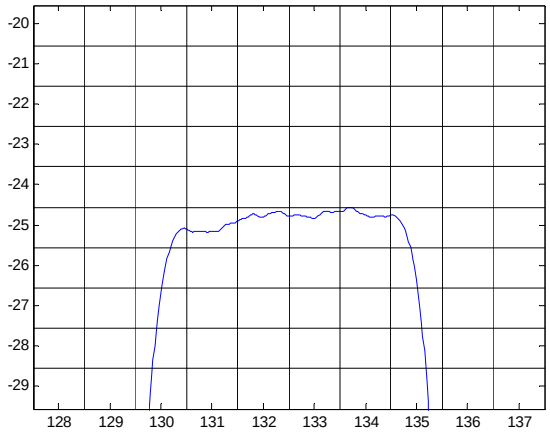
Input:1
Output:5

Typical Performance

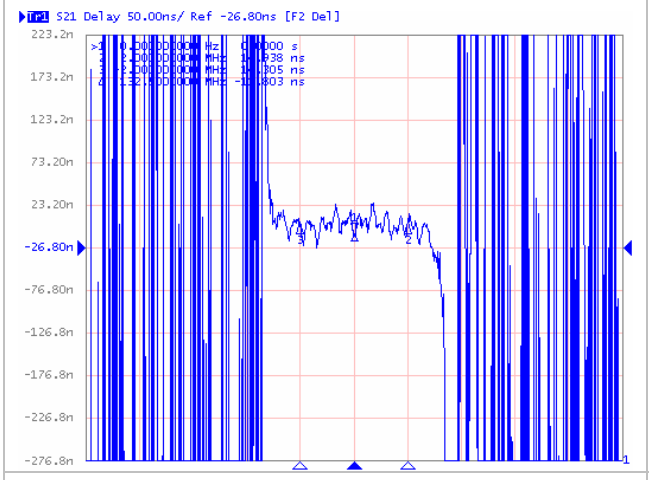
Frequency Respond



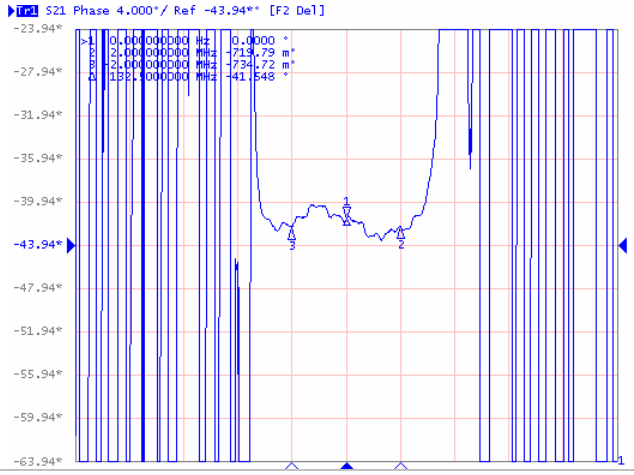
Passband Respond



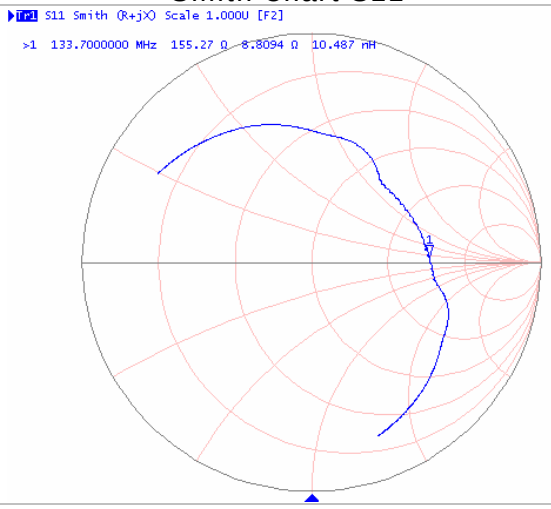
Group Delay Variation(f0±2MHz)



Phase Linearity(f0±2MHz)



Smith Chart S11



Smith Chart S22

